

LEADFRAME PACKAGE FOR SEMICONDUCTOR DEVICE

ABSTRACT

A semiconductor package comprising a leadframe which includes a die paddle having an opening formed therein. In addition to the die paddle, the leadframe includes a plurality of leads, at least one of which is disposed in spaced relation to the die paddle. The remaining leads are attached to the die paddle and extend therefrom. Electrically connected to the die paddle is the source terminal of a semiconductor die which also includes a gate terminal and a drain terminal. The gate terminal is itself electrically connected to the at least one of the leads disposed in spaced relation to the die paddle. A package body at least partially encapsulates the die paddle, the leads, and the semiconductor die such that portions of the leads and the drain terminal of the semiconductor die are exposed in the package body.